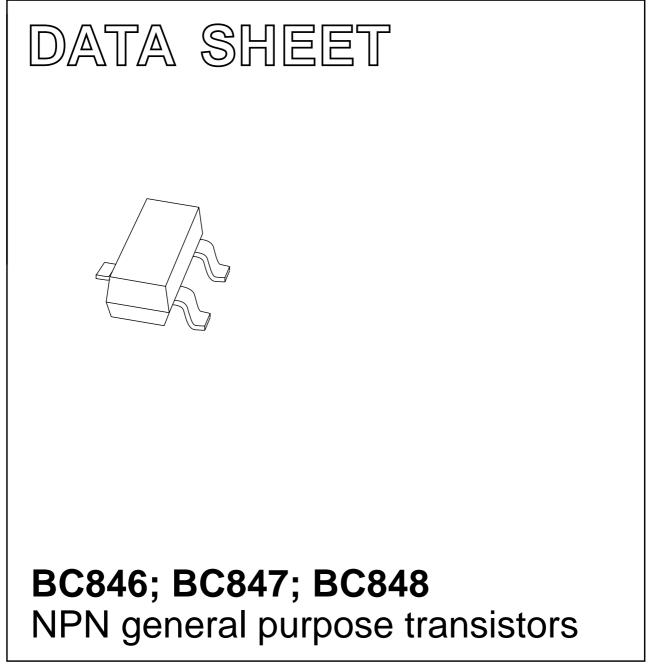
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2002 Feb 04 2004 Feb 06



BC846; BC847; BC848

NPN general purpose transistors

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 65 V).

APPLICATIONS

• General purpose switching and amplification.

DESCRIPTION

NPN transistor in a SOT23 plastic package. PNP complements: BC856, BC857 and BC858.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
BC846	1D*
BC846A	1A*
BC846B	1B*
BC847	1H*
BC847A	1E*
BC847B	1F*
BC847C	1G*
BC848B	1K*

Note

1. * = p: made in Hong Kong.

* = t: made in Malaysia.

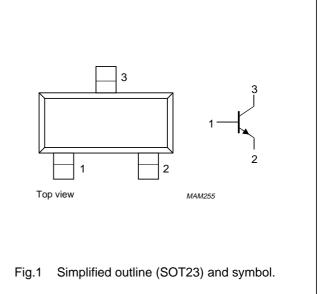
* = W: made in China.

ORDERING INFORMATION

	PACKAGE			
TYPE NUMBER	NAME	DESCRIPTION	VERSION	
BC846	_	plastic surface mounted package; 3 leads	SOT23	
BC846A				
BC846B				
BC847				
BC847A				
BC847B				
BC847C				
BC848B				

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	OL PARAMETER CONDITIONS		MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BC846		-	80	V
	BC847		-	50	V
	BC848		-	30	V
V _{CEO}	collector-emitter voltage	open base			
	BC846		-	65	V
	BC847		-	45	V
BC848			-	30	V
V _{EBO}	V _{EBO} emitter-base voltage ope				
	BC846; BC847		-	6	V
	BC848		-	5	V
I _C	collector current (DC)		-	100	mA
I _{CM}	peak collector current		-	200	mA
I _{BM}	peak base current		-	200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature – 150		150	°C	
T _{amb}	operating ambient temperature -65 +150			°C	

Note

1. Transistor mounted on an FR4 printed-circuit board, standard footprint.

THERMAL CHARACTERISTICS

SYMBOL	SYMBOL PARAMETER		VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air; note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board, standard footprint.

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CHARACTERISTICS

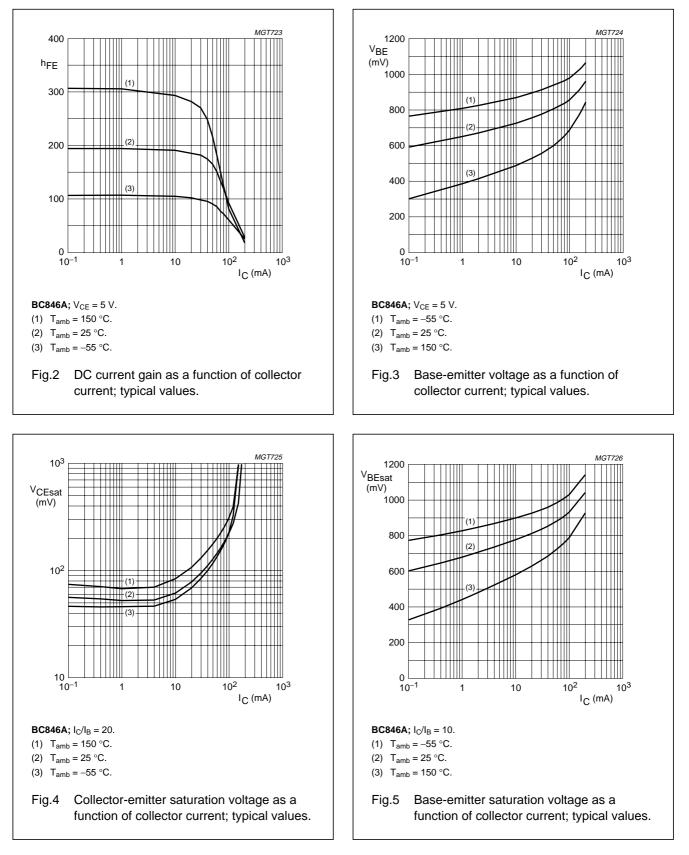
 T_{amb} = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 30 V; I _E = 0	-	-	15	nA
		$V_{CB} = 30 \text{ V}; I_E = 0;$ $T_j = 150 \text{ °C}$	-	-	5	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 V; I_{C} = 0$	-	-	100	nA
h _{FE}	DC current gain	$I_{C} = 10 \ \mu A; V_{CE} = 5 \ V$				
	BC846A; BC847A		-	90	-	
	BC846B; BC847B; BC848B		-	150	-	
	BC847C		-	270	-	
	DC current gain	I _C = 2 mA; V _{CE} = 5 V				
	BC846		110	-	450	
	BC847		110	-	800	
	BC846A; BC847A		110	180	220	
	BC846B; BC847B; BC848B		200	290	450	
	BC847C		420	520	800	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	90	250	mV
		I _C = 100 mA; I _B = 5 mA; note 1	-	200	600	mV
V _{BEsat}	base-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	700	_	mV
		I _C = 100 mA; I _B = 5 mA; note 1	-	900	-	mV
V _{BE}	base-emitter voltage	I _C = 2 mA; V _{CE} = 5 V	580	660	700	mV
		I _C = 10 mA; V _{CE} = 5 V	-	-	770	mV
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0;$ f = 1 MHz	-	2.5	-	pF
f _T	transition frequency	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 10 \text{ mA};$ f = 100 MHz	100	-	-	MHz
F	noise figure		-	2	10	dB

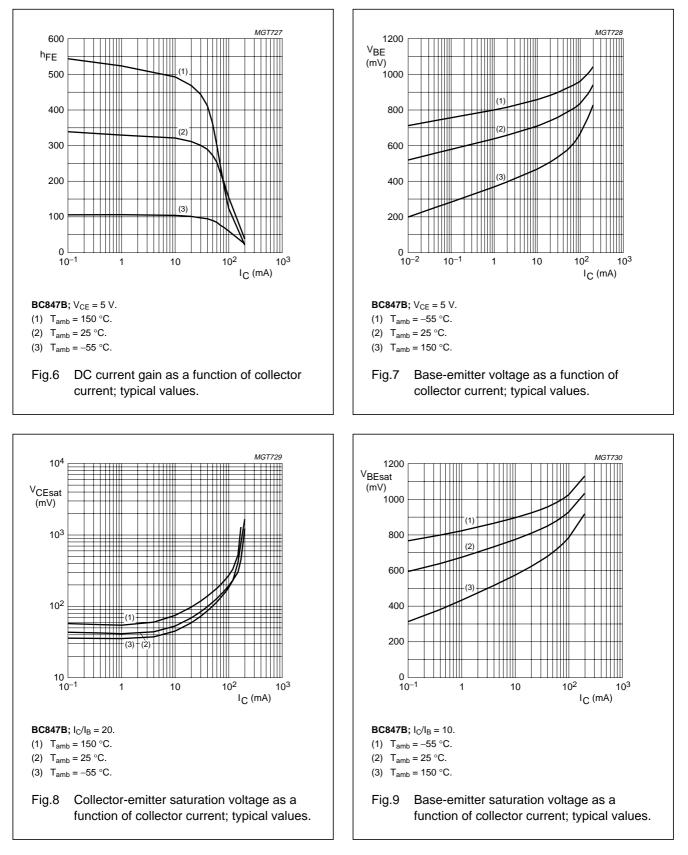
Note

1. Pulse test: $t_p \le 300 \ \mu s; \ \delta \le 0.02$.

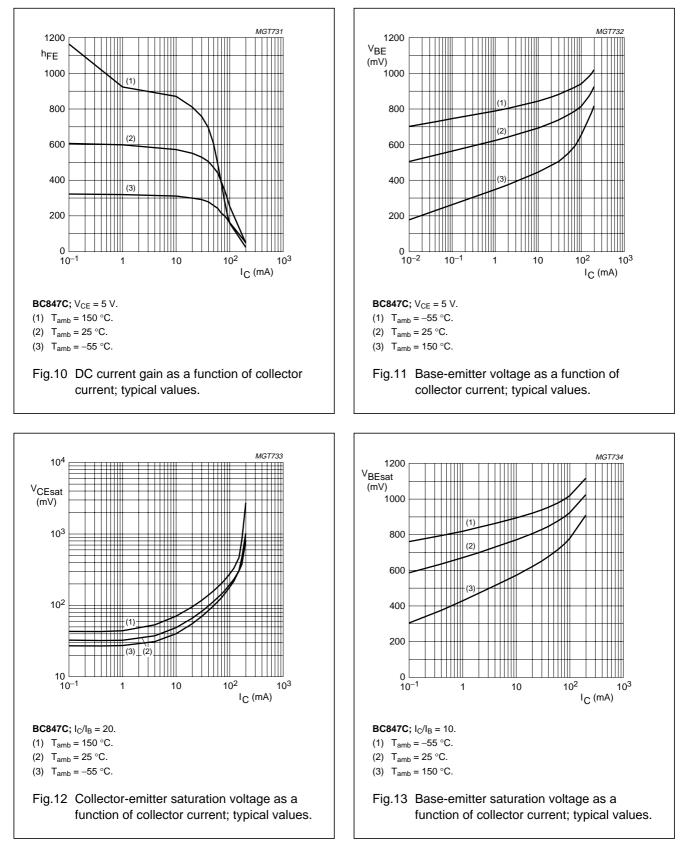
BC846; BC847; BC848



BC846; BC847; BC848

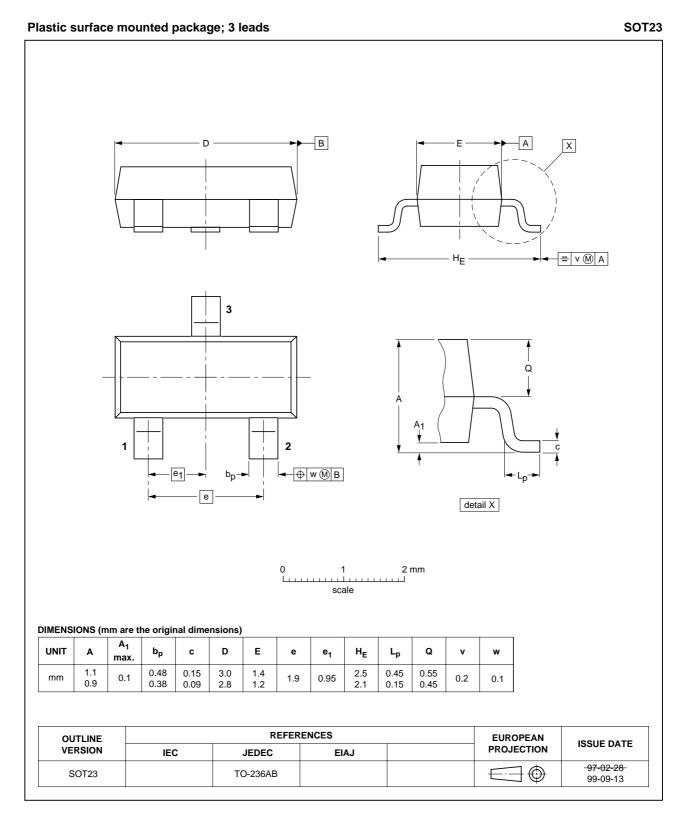


BC846; BC847; BC848



BC846; BC847; BC848

PACKAGE OUTLINE



BC846; BC847; BC848

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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